

L Number	Hits	Search Text	DB	Time stamp
6	1	("6531763").PN.	USPAT	2003/07/22 20:09
7	1	("5504035").PN.	USPAT	2003/07/22 21:02
8	61827	adhesive with (space or spaces or hole or holes or aperture or apertures or gap or gaps or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 21:28
9	2970	(adhesive with (space or spaces or hole or holes or aperture or apertures or gap or gaps or void or voids)) and (lcd or (liquid near crystal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 21:05
10	1149	((adhesive with (space or spaces or hole or holes or aperture or apertures or gap or gaps or void or voids)) and (lcd or (liquid near crystal))) and (semiconductor or chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 21:05
11	0	((adhesive with (space or spaces or hole or holes or aperture or apertures or gap or gaps or void or voids)) and (lcd or (liquid near crystal))) and (semiconductor or chip or die)) and (@ad<19960915)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 21:06
12	311	((adhesive with (space or spaces or hole or holes or aperture or apertures or gap or gaps or void or voids)) and (lcd or (liquid near crystal))) and (semiconductor or chip or die)) and (@ad<19960915)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 21:29
13	13805	(adhesive with (space or spaces or hole or holes or aperture or apertures or gap or gaps or void or voids)) and ((pressure or pressing or press or pressurizing) and heat)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 21:28
14	4155	(adhesive with (space or spaces or hole or holes or aperture or apertures or gap or gaps or void or voids)) and (adhesive with((pressure or pressing or press or pressurizing) and heat))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 21:29
15	2404	((adhesive with (space or spaces or hole or holes or aperture or apertures or gap or gaps or void or voids)) and (adhesive with((pressure or pressing or press or pressurizing) and heat))) and (@ad<19960915)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 21:29
16	506	((adhesive with (space or spaces or hole or holes or aperture or apertures or gap or gaps or void or voids)) and (adhesive with((pressure or pressing or press or pressurizing) and heat))) and (@ad<19960915)) and ((chip or die or ic or semiconductor) and (substrate or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 21:31